Total No. of Questions : 12]		SEAT No.:
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[4759] - 111

B.E. (Electronics Engineering) VLSI DESIGN

(2008 Pattern) (Semester -I)

Time: 3 Hours [Max. Marks: 100

Instructions to the candidates:

- 1) Answers to the two sections should be written in separate answer books.
- 2) Answer Q.1 or Q.2, Q.3 or Q.4, Q.5 or Q.6 from Section-I & Q.7 or Q.8, Q.9 or Q.10, Q.11 or Q.12 from Section II.
- 3) Neat diagrams must be drawn wherever necessary.
- 4) Figures to the right side indicate full marks.
- 5) Use of calculator is allowed.
- 6) Assume suitable data, if necessary.

SECTION - I

- Q1) a) Explain CMOS inverter and its transfer characteristics in detail. How to achieve symmetry in these characteristics.[8]
 - b) Design 4:1 Mux using transmission Gates. Compare it with conventional methods. [8]

OR

Q2) a) Explain the following:

[8]

- i) Hot electron effect
- ii) Body effect
- b) Explain the static & dynamic power dissipation. Derive an expression for power delay product. [8]
- **Q3)** a) Explain DRAM in detail with suitable diagram.

[8]

b) Give the classification of memory with the application in each case. [8]

OR

- **Q4)** a) Differentiate between SRAM & DRAM technologies. [8]
 - b) Explain read/write operation of 6T SRAM cell with the help of timing diagrams. [8]

P.T.O.

Q5) a)	Explain different modeling styles in VHDL coding with examples. [
b)) Compare in VHDL		
	i) Variables and Signals		
	ii) Synthesizable and Non-synthesizable statements		
	OR		
Q6) a)	Differentiate Moore and Mealy machine with suitable examples.	[9]	
b)	Write a VHDL code for a JK FF. Also write a test bench for it.	[9]	
	<u>SECTION - II</u>		
Q7) a)	Explain in detail the classification of ASIC in detail.	[8]	
~ /	Draw & explain CMOS architecture of SRAM.		
b)	•	[8]	
	OR		
Q8) a)	Explain the term	[8]	
	i) CLB		
	ii) LUT		
	iii) IOB		
	iv) Switch Matric		
b)	With neat schematic explain the architectural building blocks of CP	PLD. [8]	
Q9) a)	Explain DFT in detail. How it can be categorized? Where it is useful	ıl.[8]	
b)	What is full scan and partial scan? Explain in detail.	[8]	
	OR		
Q10) a)	Write a short note on: BIST, JTAG and TAP controller.	[8]	
b)	What are the types of fault? Explain with schematic.	[8]	
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Q11) a)		at is power optimization? Explain the methods of optimizatio ous levels.	n at [9]	
b)	Explain the following terms:			
	i)	Switch Box Routing		
	ii)	Power distribution		
	iii)	Global Routing		
		OR		
Q12) a)	Exp	plain input pad, output pad and 3 stage pad design in a chip.	[9]	
b)		at is clock skew and clock jitter? Explain different technique ck distribution.	s of [9]	
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